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General Information

Series	SMD Comm COG Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.4mm MIN
B	0.45mm +/-0.15mm
Case Code (EIA / mm)	0603 / 1608

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Dimensions	Capacitance	33 pF
Style	Measurement Condition	1 MHz 1.0Vrms
Description	Tolerance	5%
Features	Voltage DC	50 VDC
RoHS	Dielectric Withstanding Voltage	125 VDC
Termination	Temperature Range	-55/+125°C
Marking	Temp. Coefficient	COG
Typical Component Weight	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Shelf Life	Dissipation Factor	0.1% 1 MHz 1.0Vrms
MSL	Aging Rate	0% Loss/Decade Hour
	Insulation Resistance	100 GOhms

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